

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Power Dissipation	P _{PP}	84	W	8/20μs, Per Fig. 2
Peak Pulse Current	IPP	6	А	8/20μs, Per Fig. 2
ESD Protection – Contact Discharge	$V_{ESD_Contact}$	±30	kV	Standard IEC 61000-4-2
ESD Protection – Air Discharge	V_{ESD_Air}	±30	kV	Standard IEC 61000-4-2

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	PD	300	mW
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	417	°C/W
Operating Junction Temperature Range	TJ	-65 to +150	۵°
Storage Temperature Range	T _{STG}	-65 to +150	°C

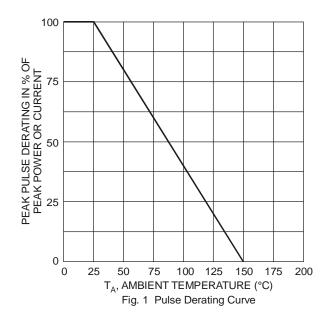
Electrical Characteristics @T_A = 25°C unless otherwise specified

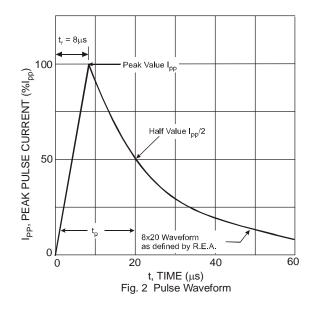
Characteristic	Symbol	Min	Тур	Max	Unit	Test Conditions
Reverse Working Voltage	V _{RWM}	-	-	5.0	V	-
Breakdown Voltage	V _{BR}	6	7	8	V	I _R = 1.0mA
Reverse Leakage Current (Note 6)	IR	-	10	100	nA	V _{RWM} = 5V
Clamping Voltage (Note 4) VCL	Vcl	-	7.0	9.0	V	$I_{PP} = 1A, t_p = 8/20 \mu s$
		-	8.7	10.7	V	$I_{PP} = 3A, t_p = 8/20 \mu s$
		-	10.5	12.0	V	$I_{PP} = 5A, t_p = 8/20 \mu s$
		-	11.5	14.0	V	$I_{PP} = 6A, t_p = 8/20 \mu s$
Differential Resistance	R _{DIF}	-	0.2	-	Ω	$I_R = 1.0A, t_p = 8/20\mu s$
Channel Input Capacitance	CT	-	15	20	pF	V _{IN} = 0V, f = 1MHz (Channel to Pin 2)

4. Measured from channel to pin 2; Non-repetitive current pulse per Fig. 2.

5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at http://www.diodes.com.

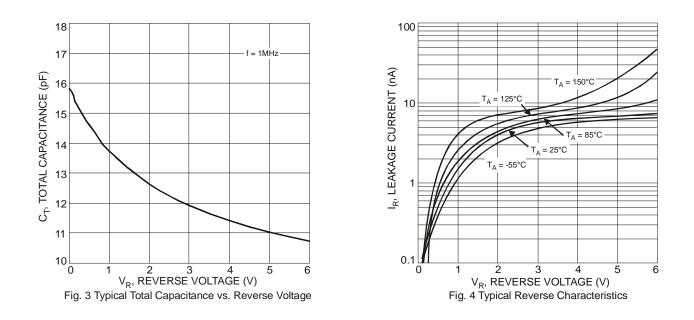
6. Short duration pulse test used to minimize self-heating effect



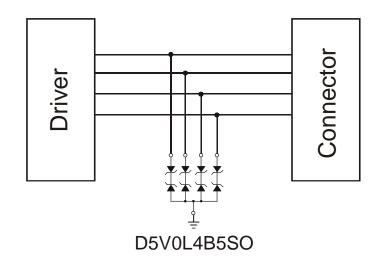


Notes:



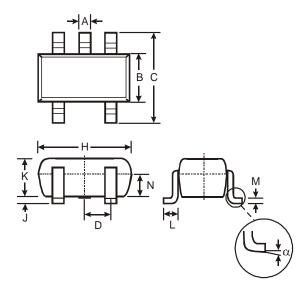


Typical Applications



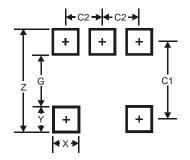


Package Outline Dimensions



SOT25					
Dim	Min	Max	Тур		
Α	0.35	0.50	0.38		
В	1.50	1.70	1.60		
С	2.70	3.00	2.80		
D			0.95		
H	2.90	3.10	3.00		
J	0.013	0.10	0.05		
К	1.00	1.30	1.10		
L	0.35	0.55	0.40		
М	0.10	0.20	0.15		
N	0.70	0.80	0.75		
α	0°	8°	_		
All D	All Dimensions in mm				

Suggested Pad Layout



Dimensions	Value (in mm)
Z	3.20
G	1.60
Х	0.55
Y	0.80
C1	2.40
C2	0.95



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